



N-Channel Logic Level Enhancement Mode Field Effect Transistor

PRODUCT SUMMARY

V _{DSS}	I _D	R _{DS(ON)} (Ω) Max
60V	0.8A	1.05 @ V _{GS} =10V
		1.30 @ V _{GS} =4.5V

FEATURES

- Super high dense cell design for low R_{DS(ON)}.
- Rugged and reliable.
- Surface Mount Package.



ABSOLUTE MAXIMUM RATINGS (T_A=25°C unless otherwise noted)

Symbol	Parameter	Limit	Units
V _{DS}	Drain-Source Voltage	60	V
V _{GS}	Gate-Source Voltage	±20	V
I _D	Drain Current-Continuous ^a	T _A =25°C	0.8
		T _A =70°C	0.64
I _{DM}	-Pulsed ^b	3	A
P _D	Maximum Power Dissipation ^a	T _A =25°C	1.25
		T _A =70°C	0.8
T _J , T _{STG}	Operating Junction and Storage Temperature Range	-55 to 150	°C

THERMAL CHARACTERISTICS

R _{θJA}	Thermal Resistance, Junction-to-Ambient ^a	100	°C/W
------------------	--	-----	------

STS6N20

Ver 1.0

ELECTRICAL CHARACTERISTICS (TA=25°C unless otherwise noted)

Symbol	Parameter	Conditions	Min	Typ	Max	Units
OFF CHARACTERISTICS						
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V , I _D =250uA	60			V
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} =48V , V _{GS} =0V			1	uA
I _{GSS}	Gate-Body Leakage Current	V _{GS} = ±20V , V _{DS} =0V			±10	uA
ON CHARACTERISTICS						
V _{GS(th)}	Gate Threshold Voltage	V _{DS} =V _{GS} , I _D =250uA	1	1.9	3	V
R _{DS(ON)}	Drain-Source On-State Resistance	V _{GS} =10V , I _D =0.4A		0.85	1.05	ohm
		V _{GS} =4.5V , I _D =0.36A		1.05	1.30	ohm
g _{FS}	Forward Transconductance	V _{DS} =10V , I _D =0.4A		1.2		S
DYNAMIC CHARACTERISTICS ^c						
C _{ISS}	Input Capacitance	V _{DS} =25V, V _{GS} =0V f=1.0MHz		41		pF
C _{OSS}	Output Capacitance			17		pF
C _{RSS}	Reverse Transfer Capacitance			9		pF
SWITCHING CHARACTERISTICS ^c						
t _{D(ON)}	Turn-On Delay Time	V _{DD} =30V I _D =0.4A V _{GS} =10V R _{GEN} = 6 ohm		6.1		ns
t _r	Rise Time			9		ns
t _{D(OFF)}	Turn-Off Delay Time			39		ns
t _f	Fall Time			10.5		ns
Q _g	Total Gate Charge	V _{DS} =30V, I _D =0.4A, V _{GS} =10V		1.5		nC
		V _{DS} =30V, I _D =0.4A, V _{GS} =4.5V		1		nC
Q _{gs}	Gate-Source Charge	V _{DS} =30V, I _D =0.4A,		0.38		nC
Q _{gd}	Gate-Drain Charge	V _{GS} =10V		0.57		nC
DRAIN-SOURCE DIODE CHARACTERISTICS AND MAXIMUM RATINGS						
V _{SD}	Diode Forward Voltage	V _{GS} =0V, I _S =0.3A		0.86	1.3	V

Notes

- Surface Mounted on FR4 Board, t ≤ 10sec.
- Pulse Test: Pulse Width ≤ 300us, Duty Cycle ≤ 2%.
- Guaranteed by design, not subject to production testing.

Jun,26,2012

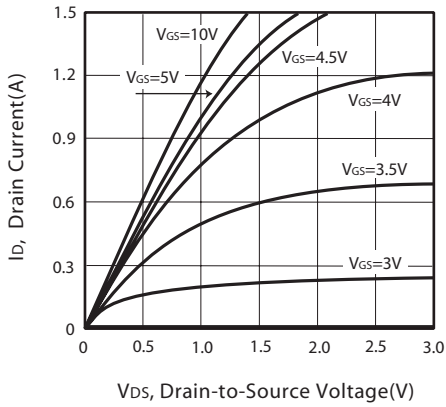


Figure 1. Output Characteristics

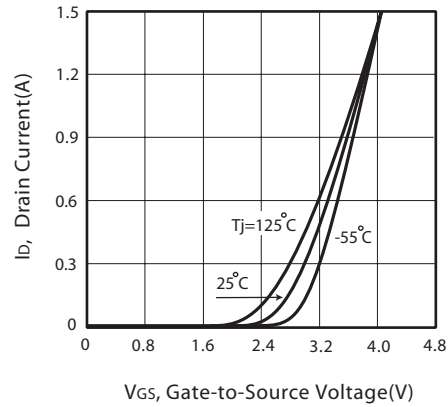


Figure 2. Transfer Characteristics

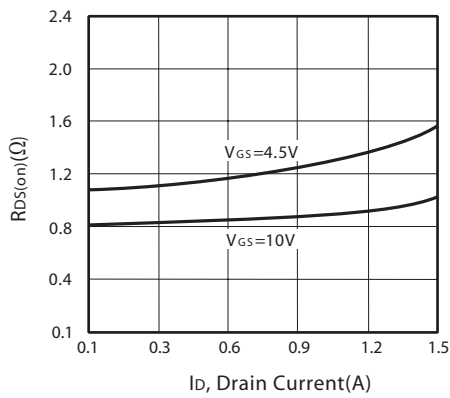


Figure 3. On-Resistance vs. Drain Current and Gate Voltage

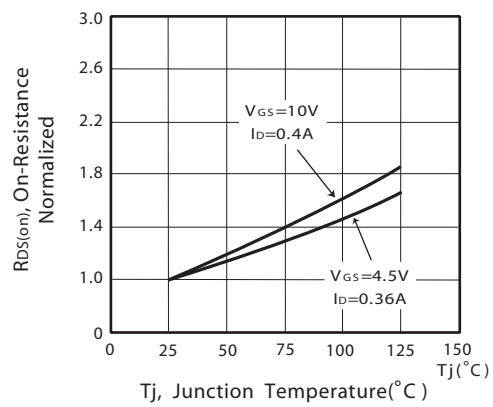


Figure 4. On-Resistance Variation with Drain Current and Temperature

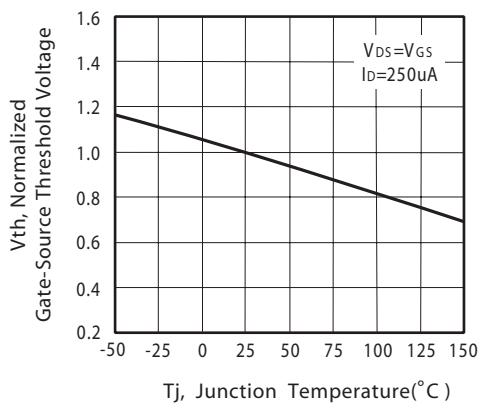


Figure 5. Gate Threshold Variation with Temperature

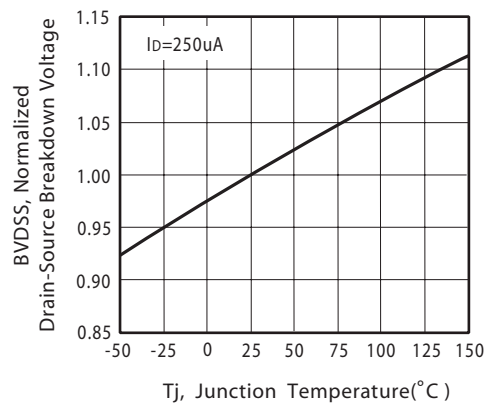


Figure 6. Breakdown Voltage Variation with Temperature

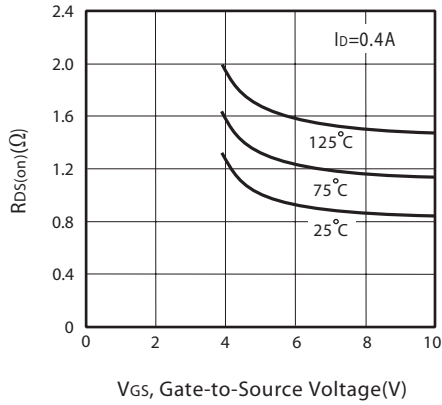


Figure 7. On-Resistance vs. Gate-Source Voltage

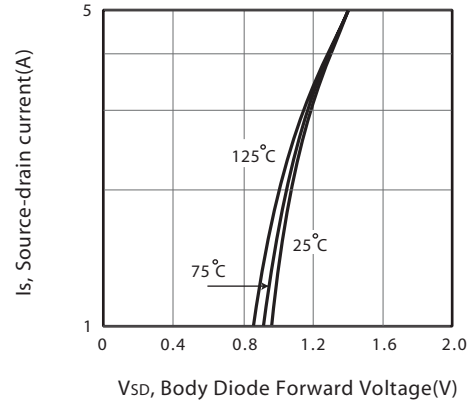


Figure 8. Body Diode Forward Voltage Variation with Source Current

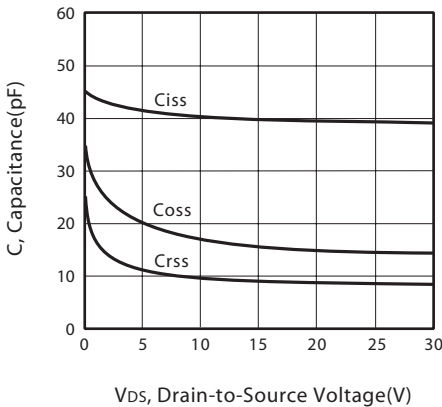


Figure 9. Capacitance

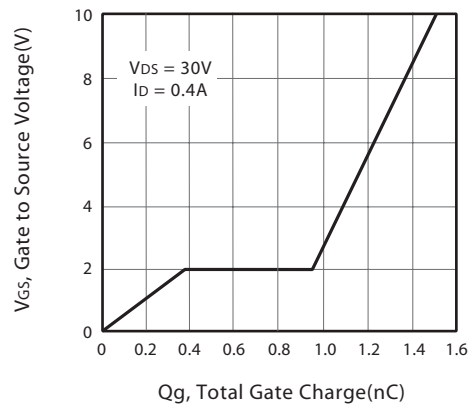


Figure 10. Gate Charge

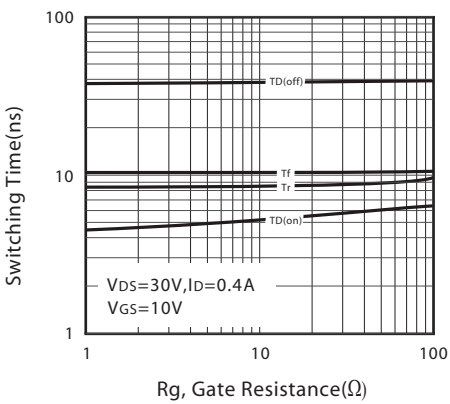


Figure 11. switching characteristics

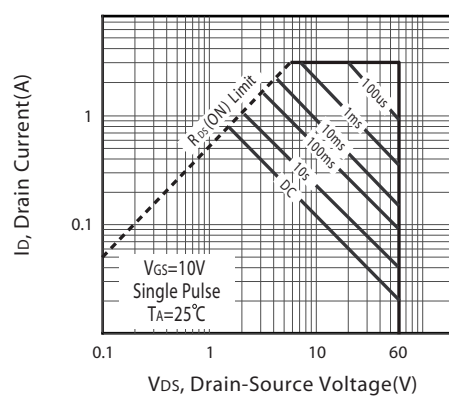


Figure 12. Maximum Safe Operating Area

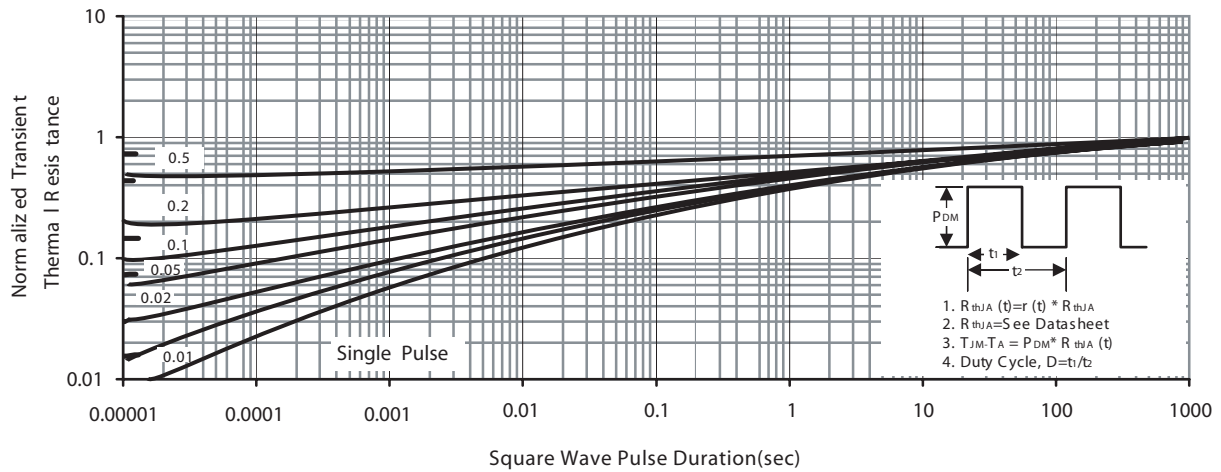
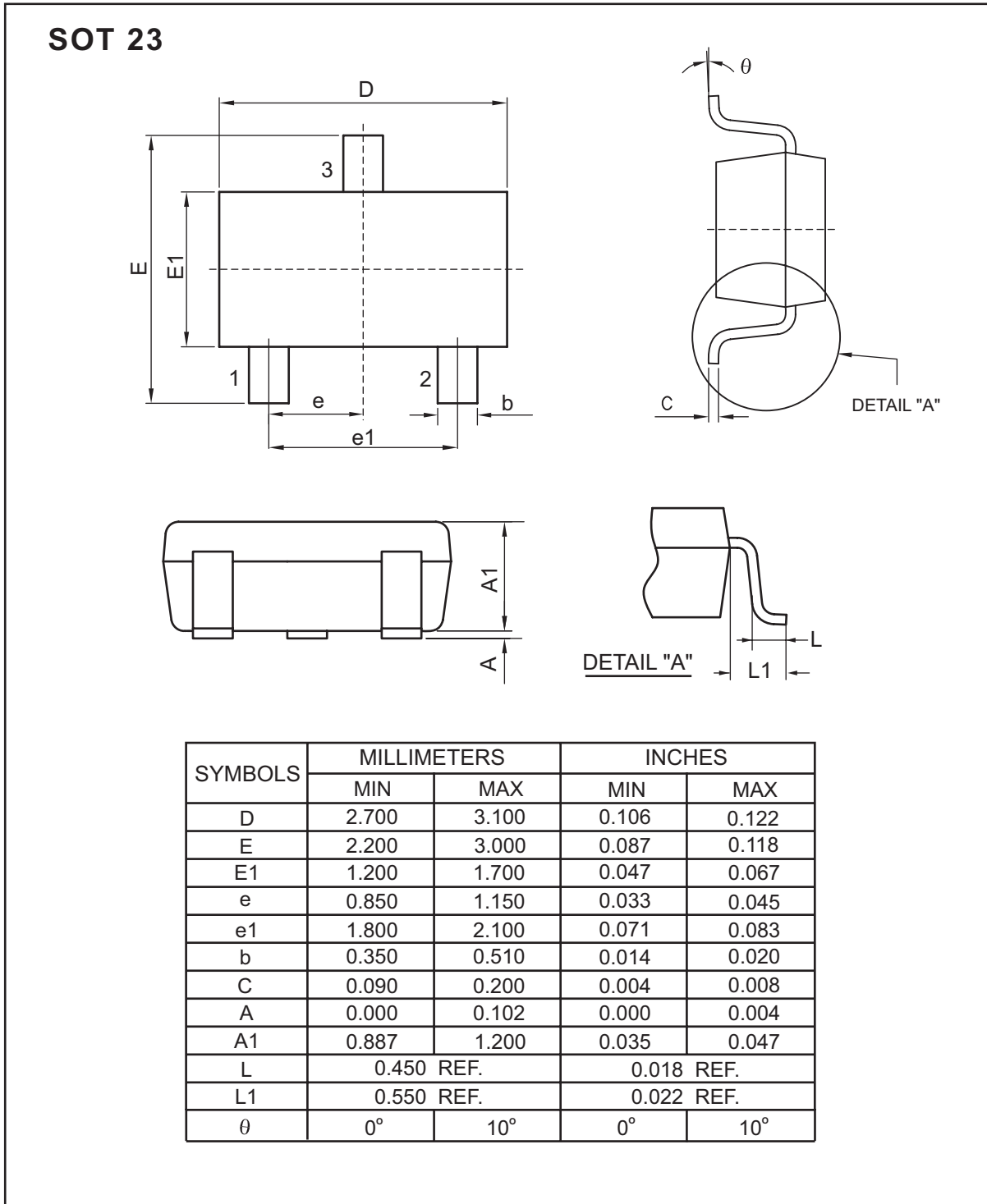


Figure 14. Normalized Thermal Transient Impedance Curve

STS6N20

Ver 1.0

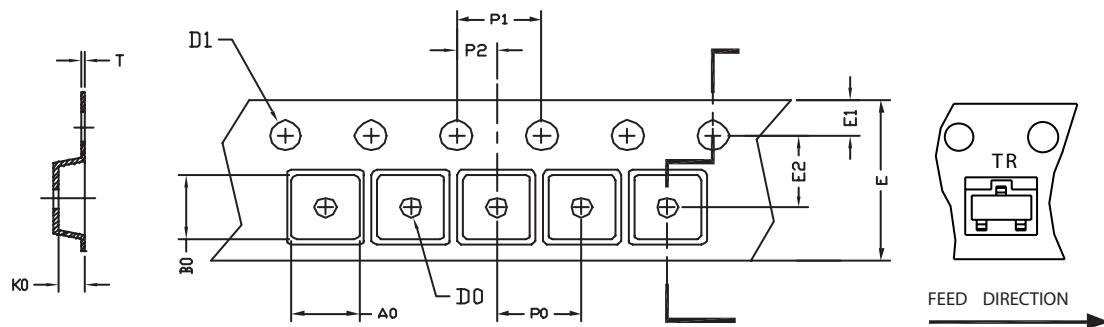
PACKAGE OUTLINE DIMENSIONS



Jun,26,2012

SOT-23 Tape and Reel Data

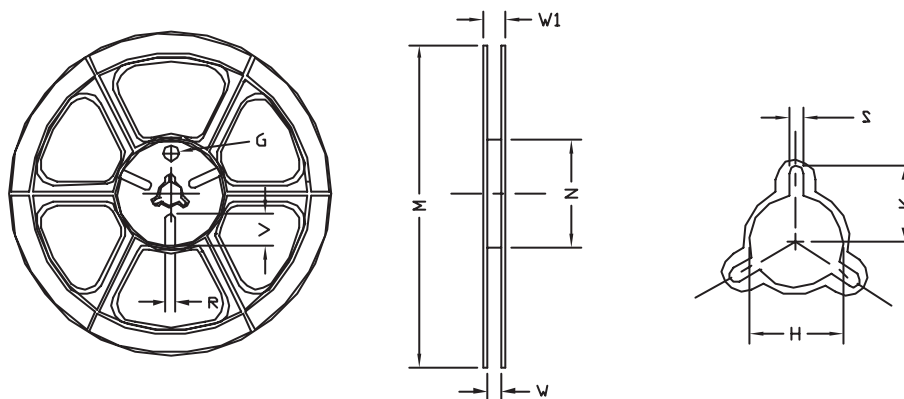
SOT-23 Carrier Tape



UNIT:mm

PACKAGE	A0	B0	K0	D0	D1	E	E1	E2	P0	P1	P2	T
SOT-23	3.20 ± 0.10	3.00 ± 0.10	1.33 ± 0.10	$\phi 1.00$ $+0.25$	$\phi 1.50$ $+0.10$	8.00 $+0.30$ -0.10	1.75 ± 0.10	3.50 ± 0.05	4.00 ± 0.10	4.00 ± 0.10	2.00 ± 0.05	0.20 ± 0.02

SOT-23 Reel



UNIT:mm

TAPE SIZE	REEL SIZE	M	N	W	W1	H	K	S	G	R	V
8mm	$\phi 178$	$\phi 178$ ± 1	$\phi 60$ ± 1	9.00 ± 0.5	12.00 ± 0.5	$\phi 13.5$ ± 0.5	10.5	2.00 ± 0.5	$\phi 10.0$	5.00	18.00